

Material Set Change:

Package Material Set		Carsem	ASE Chungli
MSOP	Die Attach	Ablestik 84-1 LMISR4	Hitachi EN4900
	Mold Compound	Sumitomo 6600H	Sumitomo G700
	Wire	0.8mil, 1.0mil and 1.2/1.3 mil Gold wire	0.8mil, 1mil and 1.2/1.3mil Gold Wire

Qualification of ASE Chungli, as an Alternate Assembly Site for MSOP Packages

Qualification Results Summary of MSOP Package at ASE Chungli

QUALIFICATION RESULT			
Test	Specification	Sample Size	Results
Temperature Cycle (TC)*	JEDEC <i>JESD22-A 104</i>	3 x 77	Pass
Autoclave (AC)*	JEDEC <i>JESD22-A 102</i>	3 x 77	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Pass
High Temperature Storage (HTS)	JEDEC <i>JESD22-A 103</i>	1 x 77	Pass

*Preconditioned per JEDEC/IPC J-STD-020